IN THE CLAIMS:

Please cancel claims 2, 5-6, and 18 without prejudice or disclaimer as to the subject matter contained therein.

Please amend the remaining claims as shown in the following claims listing:

- 1. (Currently amended) A system for cooling electronic assemblies, said system comprising:
 - an equipment enclosure configured to receive a plurality of electronic assemblies in a plurality of mounting locations; and
 - a cooling manifold mounted to said equipment enclosure and positioned to distribute chilled air to each of said plurality of electronic assemblies through a plurality of orifices;
 - wherein said cooling manifold includes a plurality of vortex tubes each positioned

 to generate and provide said chilled air to a respective one of said plurality

 of electronic assemblies through a respective one of said plurality of

 orifices.
- 2. (Cancelled)
- 3. (Currently amended) The system as recited in claim [2] 1, wherein said cooling manifold includes an intake manifold configured to distribute compressed air received at an inlet to said plurality of vortex tubes.
- 4. (Currently amended) The system as recited in claim [2] 1, wherein said cooling manifold includes an exhaust manifold configured to exhaust warm air away from said plurality of vortex tubes.

5-6. (Cancelled)

- 7. (Original) The system as recited in claim 1, wherein said cooling manifold is mounted vertically adjacent to a side wall of said equipment enclosure and wherein a length of said cooling manifold extends vertically along a height of an inside surface of said side wall.
- 8. (Original) The system as recited in claim 7, wherein each of said plurality of mounting locations is configured to receive an electronic assembly in a horizontal orientation and wherein said cooling manifold is positioned such that each of said plurality of orifices is aligned to provide chilled air to a respective one of said plurality of mounting locations.
- 9. (Original) The system as recited in claim 1, wherein said cooling manifold is mounted horizontally within said equipment enclosure and includes a length that extends around a perimeter of an inside surface of said equipment enclosure.
- 10. (Original) The system as recited in claim 9, wherein each of said plurality of mounting locations is configured to receive an electronic assembly in a vertical orientation and wherein said cooling manifold is positioned within said equipment enclosure such that said plurality of orifices direct said chilled air inward toward a center of said equipment enclosure.
- 11. (Original) The system as recited in claim 10, wherein said cooling manifold includes a plurality of vortex tubes each positioned to generate and provide said chilled air through a respective one of said plurality of orifices to said plurality of electronic assemblies.

- 12. (Original) The system as recited in claim 11, wherein said cooling manifold includes an intake manifold configured to distribute compressed air received at an inlet to said plurality of vortex tubes.
- 13. (Original) The system as recited in claim 12, wherein said cooling manifold includes an exhaust manifold configured to exhaust warm air away from said plurality of vortex tubes.
- 14. (Original) The system as recited in claim 13, wherein said equipment enclosure includes a fan positioned to cause ambient air mixed with chilled to flow over said plurality of electronic assemblies.
- 15. (Original) The system as recited in claim 1, wherein said cooling manifold is configured to distribute chilled air received at an inlet to said plurality of orifices.
- 16. (Currently amended) A method for cooling electronic assemblies, said method comprising:
 - providing an equipment enclosure configured to receive a plurality of electronic assemblies in a plurality of mounting locations; and
 - mounting a cooling manifold to said equipment enclosure and positioning said cooling manifold to distribute chilled air to each of said plurality of electronic assemblies through a plurality of orifices in said cooling manifold;
 - wherein said cooling manifold includes a plurality of vortex tubes each positioned to generate and provide said chilled air to a respective one of said plurality of electronic assemblies through a respective one of said plurality of orifices.

- 17. The method as recited in claim 16 further comprising forcing chilled air into an inlet of said cooling manifold.
- 18. (Cancelled)
- 19. (Original) The method as recited in claim 16 further comprising distributing through an intake manifold compressed air received at an inlet to said plurality of vortex tubes.
- 20. (Original) The method as recited in claim 17 further comprising exhausting warm air away from said plurality of vortex tubes through an exhaust manifold.
- 21. (Original) A cooling manifold for providing chilled air to electronic equipment, said cooling manifold comprising:
 - a plurality of vortex tubes distributed along a length of said cooling manifold, wherein each of said plurality of vortex tubes is configured to generate a portion of said chilled air;
 - an intake manifold configured to distribute compressed air received at an inlet to said plurality of vortex tubes;
 - an exhaust manifold configured to exhaust warm air away from said plurality of vortex tubes.